

UC1856 UC2856 UC3856

Improved Current Mode PWM Controller

FEATURES

- Pin-for-Pin Compatible With the UC3846
- 65ns Typical Delay From Shutdown to Outputs, and 50ns Typical Delay From Sync to Outputs
- Improved Current Sense Amplifier With Reduced Noise Sensitivity
- Differential Current Sense with 3V Common Mode Range
- Trimmed Oscillator Discharge Current for Accurate Deadband Control
- Accurate 1V Shutdown Threshold
- High Current Dual Totem Pole Outputs (1.5A peak)
- TTL Compatible Oscillator SYNC Pin Thresholds
- 4kV ESD Protection

DESCRIPTION

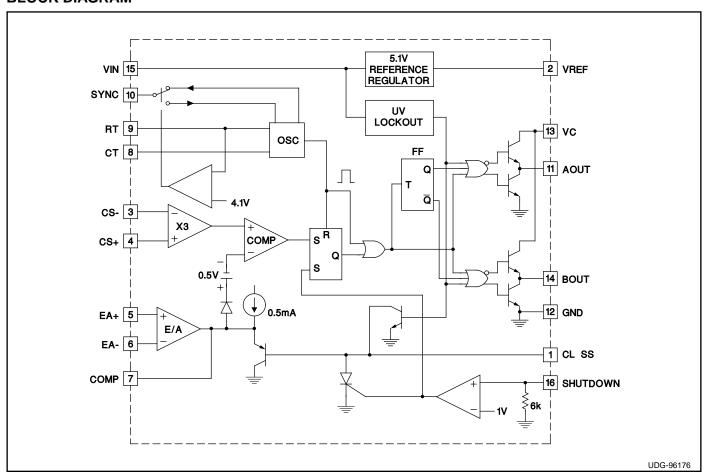
The UC3856 is a high performance version of the popular UC3846 series of current mode controllers, and is intended for both design upgrades and new applications where speed and accuracy are important. All input to output delays have been minimized, and the current sense output is slew rate limited to reduce noise sensitivity. Fast 1.5A peak output stages have been added to allow rapid switching of power FETs.

A low impedance TTL compatible sync output has been implemented with a tri-state function when used as a sync input.

Internal chip grounding has been improved to minimize internal "noise" caused when driving large capacitive loads. This, in conjunction with the improved differential current sense amplifier results in enhanced noise immunity.

Other features include a trimmed oscillator current (8%) for accurate frequency and dead time control; a 1V, 5% shutdown threshold; and 4kV minimum ESD protection on all pins.

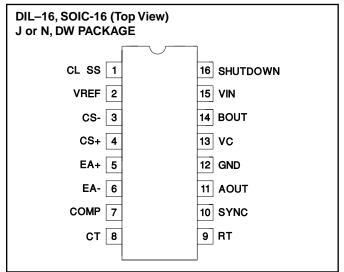
BLOCK DIAGRAM

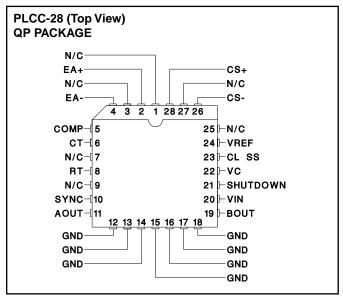


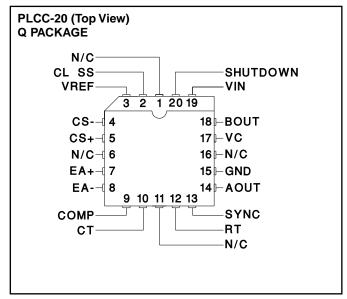
ABSOLUTE MAXIMUM RATINGS

Supply Voltage	+40V
Collector Supply Voltage	
Output Current, Source or Sink	
DC	0.5A
Pulse (0.5μs)	2.0A
Error Amp Inputs	
Shutdown Input	0.3V to +10V
Current Sense Inputs	0.3V to +3V
SYNC Output Current	±10mA
Error Amplifier Output Current	–5mA
Soft Start Sink Current	
Oscillator Charging Current	5mA
Power Dissipation at T _A = 25°C (Note 2)	1000mW
Power Dissipation at Tc = 25°C (Note 2)	2000mW
Junction Temperature5	
Storage Temperature Range6	35°C to +150°C
Lead Temperature (Soldering, 10 sec.)	+300°C
All voltages are with respect to Ground. Currents	are positive
into, negative out of the specified terminal. Const	ult packaging
section of databook for thermal limitations and co	onsiderations of
package.	

CONNECTION DIAGRAMS







ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for $TA = -55^{\circ}C$ to $+125^{\circ}C$ for UC1856; $-40^{\circ}C$ to $+85^{\circ}C$ for the UC2856; and $0^{\circ}C$ to $+70^{\circ}C$ for the UC3856, VIN = 15V, RT = 10k, CT = 1nF, TA = TJ.

		UC1	856/UC	2856		UC3856	6	
PARAMETER	TEST CONDITIONS	MIN	MIN TYP MAX		MIN TYP		MAX	UNITS
Reference Section							•	
Output Voltage	T _J = 25°C, lo = 1mA	5.05	5.10	5.15	5.00	5.10	5.20	V
Line Regulation	VIN = 8V to 40V			20			20	mV
Load Regulation	Io = -1mA to -10mA			15			15	mV
Total Output Variation	Line, Load, and Temperature	5.00		5.20	4.95		5.25	V
Output Noise Voltage	10Hz < f < 10kHz, T _J = 25°C		50			50		μV
Long Term Stability	T _J = 125°C, 1000 Hrs (Note 2)		5	25		5	25	mV
Short Circuit Current	VREF = 0V	-25	-45	-65	-25	-45	-65	mA
Oscillator Section	·							
Initial Accuracy	T _J = 25°C	180	200	220	180	200	220	kHz
	Over Operating Range	170		230	170		230	kHz

ELECTRICAL CHARACTERISTICS (cont.) Unless otherwise stated, these specifications apply for $TA = -55^{\circ}C$ to $+125^{\circ}C$ for UC1856; $-40^{\circ}C$ to $+85^{\circ}C$ for the UC2856; and $0^{\circ}C$ to $+70^{\circ}C$ for the UC3856, VIN = 15V, RT = 10k, CT = 1nF, TA = TJ.

		UC1856/UC2856				UC385	6	
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Oscillator Section (cont.)				1		1		
Voltage Stability	VIN = 8V to 40V			2			2	%
Discharge Current	T _J = 25°C, V _{CT} = 2V	7.5	8.0	8.8	7.5	8.0	8.8	mA
S	VcT = 2V	6.7	8.0	8.8	6.7	8.0	8.8	mA
Sync Output High Level	Io = -1mA	2.4	3.6		2.4	3.6		V
Sync Output Low Level	Io = +1mA		0.2	0.4		0.2	0.4	V
Sync Input High Level	CT = 0V, RT = VREF	2.0	1.5		2.0	1.5		V
Sync Input Low Level	CT = 0V, RT = VREF		1.5	0.8		1.5	0.8	V
Sync Input Current	CT = 0V, RT = VREF		1	10		1	10	μA
Cyric input Current	$V_{SYNC} = 5V$		'			'	10	μιτ
Sync Delay to Outputs	CT = 0V, RT = VREF		50	100		50	100	ns
Cyric Dolay to Catpate	VSYNC = 0.8V to 2V			100			100	1.0
Error Amplifier Section	10.00					1		<u> </u>
Input Offset Voltage	Vcm = 2V			5			10	mV
Input Bias Current				-1			-1	μА
Input Offset Current				500			500	nA
Common Mode Range	VIN = 8V to 40V	0		VIN – 2	0		VIN – 2	V
Open Loop Gain	Vo = 1.2V to 3V	80	100		80	100		dB
Unity Gain Bandwidth	T _J = 25°C	1	1.5		1	1.5		MHz
CMRR	VcM = 0V to 38V, VIN = 40V	75	100		75	100		dB
PSRR	VIN = 8V to 40V	80	100		80	100		dB
Output Sink Current	VID = -15mV, VCOMP = 1.2V	5	10		5	10		mA
Output Source Current	VID = 15mV, VCOMP = 2.5V	-0.4	-0.5		-0.4	-0.5		mA
Output High Level	VID = 50mV, RL (COMP) = 15k	4.3	4.6	4.9	4.3	4.6	4.9	V
Output Low Level	VID = -50mV, RL (COMP) = 15k		0.7	1		0.7	1	V
Current Sense Amplifier Section	<u> </u>			1		1	1	
Amplifier Gain	Vcs-= 0V, CL SS Open (Notes 3,4)	2.5	2.75	3.0	2.5	2.75	3.0	V/V
Maximum Differential	CL SS Open (Note 3)	1.1	1.2		1.1	1.2		V
Input Signal (Vcs+ - Vcs-)	RL (COMP) = 15k							
Input Offset Voltage	Vcl ss = 0.5V		5	35		5	35	mV
input Onset voltage	COMP Open (Note 3)		3	33		3	33	1111
CMRR	Vcm = 0V to 3V	60			60			dB
PSRR	VIN = 8V to 40V	60			60			dB
Input Bias Current	Vcl ss = 0.5V, COMP Open (Note 3)			-1	-3	-1	-3	μΑ
Input Offset Current	Vcl ss = 0.5V, COMP Open (Note 3)			1	_		1	mA
Input Common Mode Range	, com spen (0		3	0		3	V
Delay to Outputs	VEA+ = VREF, EA- = 0V		120	250		120	250	ns
	CS+ - CS- = 0V to 1.5V							
Current Limit Adjust Section	001 00 - 00 1.00					l		
Current Limit Offset	Vcs- = 0V	0.43	0.5	0.57	0.43	0.5	0.57	V
	Vcs+ = 0V, COMP = Open (Note 3)							
Input Bias Current	VEA+ = VREF, VEA- = 0V		-10	-30		-10	-30	μΑ
Shutdown Terminal Section								
Threshold Voltage		0.95	1.00	1.05	0.95	1.00	1.05	V
Input Voltage Range		0	<u> </u>	5	0		5	V

ELECTRICAL CHARACTERISTICS (cont.) Unless otherwise stated, these specifications apply for $TA = -55^{\circ}C$ to $+125^{\circ}C$ for UC1856; $-40^{\circ}C$ to $+85^{\circ}C$ for the UC2856; and $0^{\circ}C$ to $+70^{\circ}C$ for the UC3856, VIN = 15V, RT = 10k, CT = 1nF, TA = TJ.

		UC	1856/UC	2856				
PARAMETER	TEST CONDITIONS	MIN	MIN TYP		MIN	TYP	MAX	UNITS
Shutdown Terminal Section (con	t.)				•			
Minimum Latching	(Note 5)	3	1.5		3	1.5		mA
Current (IcL ss)								
Maximum Non-Latching	(Note 6)		1.5	0.8		1.5	0.8	mA
Current (IcL ss)								
Delay to Outputs	VSHUTDOWN = 0 to 1.3V		65	110		65	110	ns
Output Section					•			
Collector-Emitter Voltage		40			40			V
Off-State Bias Current	VC = 40V			250			250	μА
Output Low Level	IOUT = 20mA		0.1	0.5		0.1	0.5	V
	IOUT = 200mA		0.5	2.6		0.5	2.6	V
Output High Level	IOUT = -20mA	12.5	13.2		12.5	13.2		V
	IOUT = -200mA	12	13.1		12	13.1		V
Rise Time	C1 = 1nF		40	80		40	80	ns
Fall Time	C1 = 1nF		40	80		40	80	ns
UVLO Low Saturation	VIN = 0V, IOUT = 20mA		0.8	1.5		0.8	1.5	V
PWM Section								
Maximum Duty Cycle		45	47	50	45	47	50	%
Minimum Duty Cycle				0			0	%
Undervoltage Lockout Section								
Startup Threshold			7.7	8.0		7.7	8.0	V
Threshold Hysterisis			0.7			0.7		V
Total Standby Current								
Supply Current			18	23		18	23	mA
		-	-					•

Note 1: All voltages are with respect to GND. Currents are positive into, negative out of the specified terminal.

Note 2: This parameter, although guaranteed over the recommended operating conditions is not 100% tested in production.

Note 3: Parameter measured at trip point of latch with VEA+ = VREF, VEA- = 0V.

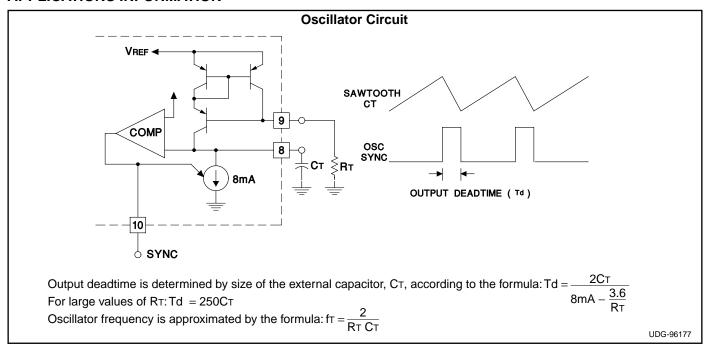
Note 4: Amplifier gain defined as:

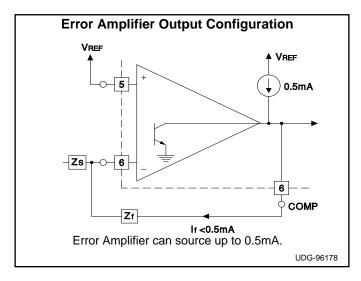
 $G = \frac{\Delta V_{COMP}}{\Delta V_{CS+}};$ $\Delta V_{CS-} = 0V \text{ to } 1.0V$

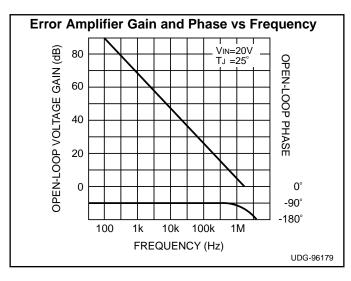
Note 5: Current into CL SS guaranteed to latch circuit into shutdown state.

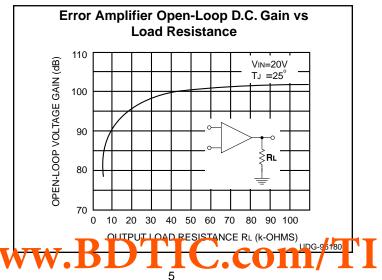
Note 6: Current into CL SS guaranteed not to latch circuit into shutdown state.

APPLICATIONS INFORMATION

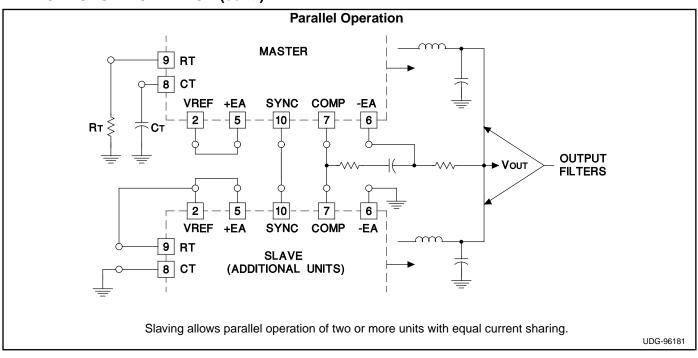


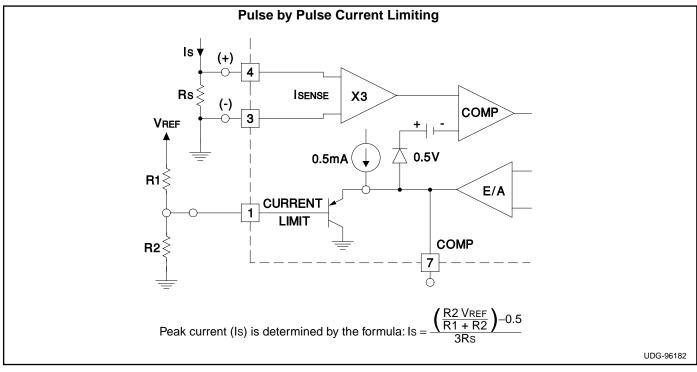




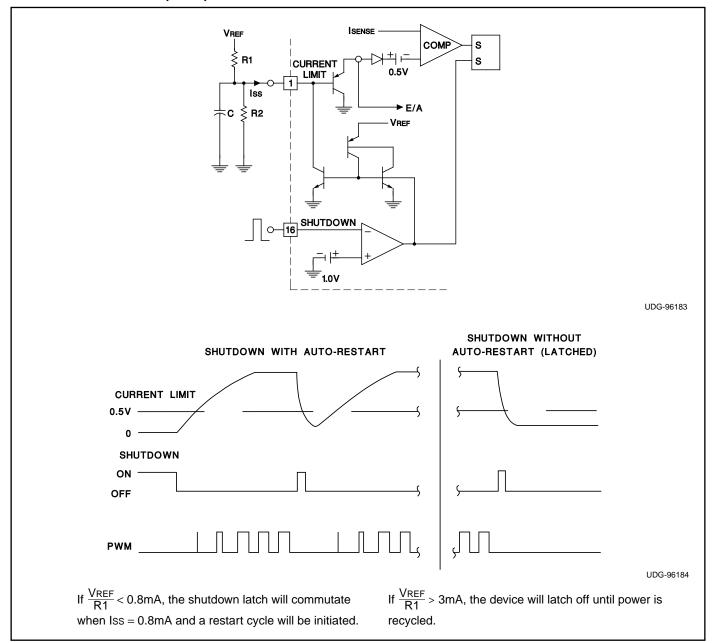


APPLICATIONS INFORMATION (cont.)



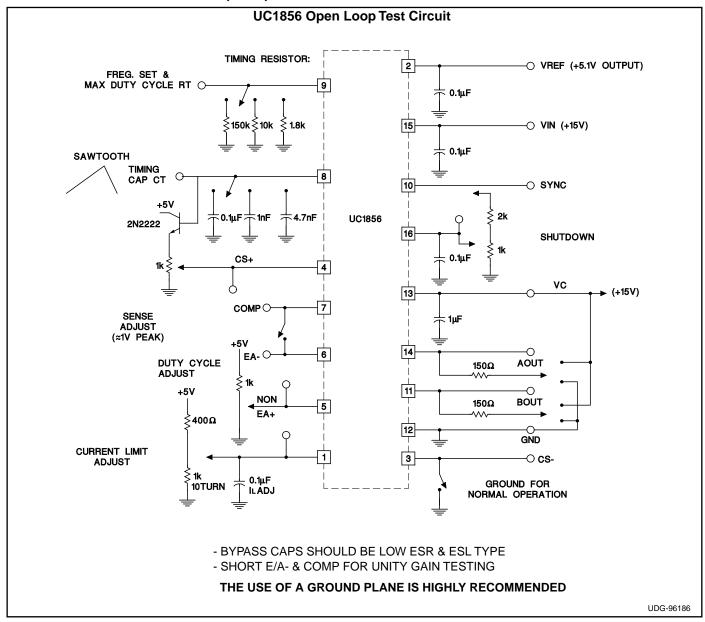


APPLICATIONS DATA (cont.)



Current Sense Amplifier Connections Is R R CURRENT SENSE A small RC filter may be required in some applications to reduce switch transients. Differential input allows reince, also set sing.

APPLICATIONS INFORMATION (cont.)



29-May-2010

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9453001M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
5962-9453001MEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Purchase Samples
UC1856J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Contact TI Distributor or Sales Office
UC1856J883B	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Contact TI Distributor or Sales Office
UC1856L	OBSOLETE	TO/SOT	L	28		TBD	Call TI	Call TI	Replaced by UC1856L20
UC1856L20	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Contact TI Distributor or Sales Office
UC1856L20883B	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Contact TI Distributor or Sales Office
UC1856L883B	OBSOLETE	TO/SOT	L	28		TBD	Call TI	Call TI	Replaced by UC1856L20883B
UC2856DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Request Free Samples
UC2856DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Request Free Samples
UC2856DWTR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UC2856DWTRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UC2856J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Contact TI Distributor or Sales Office
UC2856N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Request Free Samples
UC2856NG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Request Free Samples
UC3856DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Request Free Samples
UC3856DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Request Free Samples
UC3856DWTR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
UC3856DWTRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UC3856N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Request Free Samples
UC3856NG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Request Free Samples
UC3856Q	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	Purchase Samples
UC3856QG3	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	Purchase Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF UC1856, UC2856, UC2856M, UC3856:







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● Catalog: UC3856, UC2856

Automotive: UC2856-Q1, UC2856-Q1

● Military: UC2856M, UC1856

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

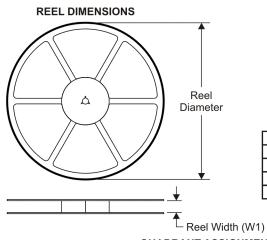
• Military - QML certified for Military and Defense Applications

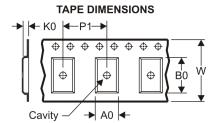




29-Jul-2008

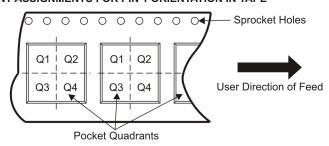
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

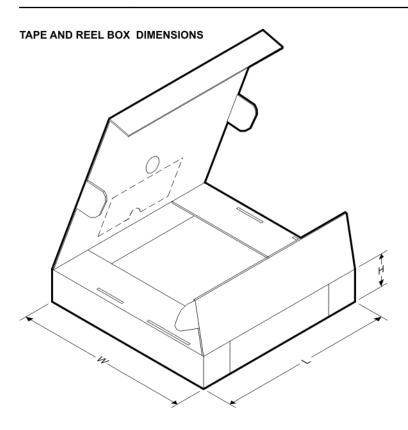


*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter	Reel Width	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2856DWTR	SOIC	DW	16	2000	(mm) 330.0	W1 (mm) 16.4	10.85	10.8	2.7	12.0	16.0	Q1
UC3856DWTR	SOIC	DW	16	2000	330.0	16.4	10.85	10.8	2.7	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

29-Jul-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2856DWTR	SOIC	DW	16	2000	346.0	346.0	33.0
UC3856DWTR	SOIC	DW	16	2000	346.0	346.0	33.0

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